

Title (en)

ELECTROLYTIC SOLUTION FOR ELECTROCHEMICAL DEPOSITION OF GOLD AND ITS ALLOYS

Title (de)

ELEKTROLYTISCHES BAD ZUM ELEKTROCHEMISCHEN ABSCHIEDEN VON GOLD UND GOLDBLEGIERUNGEN

Title (fr)

BAIN ELECTROLYTIQUE POUR LE DEPOT ELECTROCHIMIQUE DE L'OR ET DE SES ALLIAGES

Publication

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Application

**EP 02774881 A 20020822**

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Abstract (en)

[origin: WO03018880A1] The invention concerns an aqueous electrolytic solution for electrochemical deposition of gold or of its alloys comprising at least a soluble gold compound designed for electrolytic deposition and, optionally at least a secondary metal compound designed for co-deposition in the form of a gold alloy. The invention is characterised in that it further comprises 0.3 to 3 moles per mole of gold contained in the electrolytic solution of an organic compound comprising one or two aldehyde functions, said organic compound being: either glyoxal, or an organic compound comprising 3 to 20 carbon atoms and one or two aldehyde functions in the form: of a saturated or unsaturated, linear or branched aliphatic group, or a group containing at least a saturated, unsaturated or aromatic cycle, said organic compound may further include at least a heteroelement selected among oxygen, nitrogen, sulphur and phosphorus or be in the form of a salt, in particular a sulphonate. The presence of said organic compound enables to increase the speed of electrodeposition of gold or of its alloys and/or to decrease contact resistance. The invention also concerns a method for electrodeposition of gold or of a gold alloy comprising electrolysis of such an electrolytic solution.

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